



FULLY AUTOMATIC SINGLE SPINDLE DICING SAWS

7302

2" Spindle

For silicon / glass wafers



Features & Benefits

- Internal air flow management management minimizing product contamination
- Multi panel dicing
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Custom process solution
- UV LED curing system
- Broken Blade detector (for 2" spindle)
- Exhaust impeller
- High power 2" spindle up to 2.2KW
- Height Measuring Tool (HMT)
- SECS GEM communication protocol

Workpiece Size	Ø 12" or 9" X 12"	
Spindle	60K rpm / 1.8 kW or 2.2KW	
Blade Size	2" - 3"	
Y Axis	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
	Cutting Range	350 mm
X Axis	Air Slide	
Z Axis	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. Stroke	50 mm (for 2.188" blade OD)
Ø Axis	Repeatability	4 arc-sec
	Stroke	380°
Cleaning Station	Spinning speed	Full rinse and dry cycle 100-2,000 rpm
	Cleaning Method	Atomized cleaning capabilities
	Utilities	200-240 VAC, 50/60 Hz, single phase
Dimensions	(W x D x H) mm	1100 x 1785 x 1700
	Weight	1,350kg

Materials:

Silicon Wafers | PCB | QFN and BGA multi panels | LED Packages

7234

4" Spindle

Hard material dicing such as glass, ceramic and more



Features & Benefits

- Efficient wafer handling system
- Continuous digital magnifications vision system
- Blade wear prediction algorithm reduces height measurement time and increases UPH
- Atomized wafer cleaning technology for superior process results

Workpiece Size	Ø 12" or 253mm X 243mm	
Spindle	30K rpm / 2.5 kW	
Blade Size	4" - 5"	
Y Axis	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
	Cutting Range	350 mm
X Axis	Air Slide	
Z Axis	Resolution	0.2 µm
	Repeatability	1.0 µm
Ø Axis	Repeatability	4 arc-sec
	Stroke	380°
Cleaning Station	Spinning speed	Full rinse and dry cycle 100-2,000 rpm
	Cleaning Method	Atomized cleaning capabilities
	Utilities	200-240 VAC, 50/60 Hz, single phase
Dimensions	(W x D x H) mm	1100 x 1785 x 1700
	Weight	1,350kg

Materials:

Glass | Sapphire and other hard materials | Ceramic substrates | Alumina | Hybrids | Thick film devices and more